CMKD6001

SURFACE MOUNT
TRIPLE ISOLATED
ULTRA LOW LEAKAGE
SILICON SWITCHING DIODES





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMKD6001 type contains three (3) Isolated Silicon Switching Diodes, manufactured by the epitaxial planar process, epoxy molded in a ULTRAmini™ surface mount package, designed for switching applications requiring extremely low leakage.

MARKING CODE: K01

MAXIMUM RATINGS: (T _A =25°C) Continuous Reverse Voltage	SYMBOL VR	75	UNITS V
Peak Repetitive Reverse Voltage	V_{RRM}	100	V
Continuous Forward Current	I _F	250	mA
Peak Repetitive Forward Current	I _{FRM}	500	mA
Peak Forward Surge Current, tp=1.0µs	I _{FSM}	4.0	Α
Peak Forward Surge Current, tp=1.0s	I _{FSM}	1.0	Α
Power Dissipation	P_{D}	250	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	ΘιΔ	500	°C/W

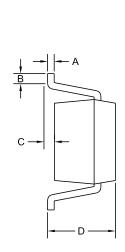
ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted) SYMBOL TEST CONDITIONS UNITS MAX I_R V_R=75V 500 рΑ I_R=100μA 100 BV_R V V_{F} I_E=1.0mA 0.85 V I_F=10mA 0.95 V_{F} V I_E=100mA V_{F} 1.1 $V_R=0$, f=1.0MHz C_T 2.0 рF $I_R=I_F=10$ mA, $I_{rr}=1.0$ mA, $R_I=100$ Ω 3.0 t_{rr} μs

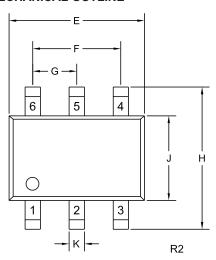
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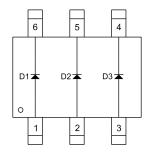


SOT-363 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
Α	0.004	0.010	0.10	0.25		
В	0.005	-	0.12	-		
С	0.000	0.004	0.00	0.10		
D	0.031	0.043	0.80	1.10		
E	0.071	0.087	1.80	2.20		
F	0.051		1.30			
G	0.026		0.65			
Н	0.075	0.091	1.90	2.30		
J	0.043	0.055	1.10	1.40		
K	0.006	0.012	0.15	0.30		

SOT-363 (REV: R2)

LEAD CODE:

- 1) Anode D1
- 2) Anode D2 3) Anode D3
- 4) Cathode D3
- 5) Cathode D2
- 6) Cathode D1

MARKING CODE: K01

R5 (9-May 2011)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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